



**TEXAS INSTRUMENTS**

TI DN 2510301  
Rev B  
August 2009

# **Circuit Card Assembly DLP® Discovery™ 4100 Main Board**

## **DLP Discovery 4100 Circuit Card Assembly Main Board**

### **Revision History**

<b>Rev</b>	<b>Section</b>	<b>Revisions</b>
<b>A</b>	<b>All</b>	<b>Initial release</b>
<b>B</b>		<b>Updated schematic and BOM_CCA</b>

**TABLE OF CONTENTS**

<b>1. CONFIGURATION SUMMARY .....</b>	<b>4</b>
<b>2. RELATED DOCUMENTS.....</b>	<b>4</b>
<b>3. NOTES .....</b>	<b>4</b>
<b>BILL OF MATERIAL.....</b>	<b>5</b>
<b>4. CROSS REFERENCE.....</b>	<b>5</b>
<b>6. ASSEMBLY VIEW .....</b>	<b>6</b>
6.1 PRIMARY SIDE.....	6
6.2 SECONDARY SIDE.....	7

## **DLP Discovery 4100 Circuit Card Assembly Main Board**

### **1. Configuration Summary**

Dash #	Configuration Description – Reference 2510301-bom_CCA.xls
-1	Initial
-2	Updated BOM_CCA and schematic to rev B

### **2. Related Documents**

#### Texas Instruments Documents

Dwg. Number	Document Name
2510300	PCB, DMD Discovery 4100
2510299	ESD(schematic) Rev B, DMD Discovery 4100
2510443	DDC4100 Datasheet
2506593	DAD2000 Datasheet

### **3. Notes**

1. This PWB contains devices that are electrostatic discharge sensitive.
2. Mark the appropriate msn. Method and placement location optional.
3. Mark dash number and revision letter of cca. Method and placement location optional.
4. Primary side components have reference designators numbered less than 500. Secondary side components have reference designators numbered greater than 500.
5. Reference designators not installed.
6. Equivalent or better part may be substituted.
7. Workmanship shall be in accordance with ansi/IPC-A-610B class 2 and ANSI/J-STD-001A class 2.
8. Solder times and temperatures must be in conformance with PWB UL component recognition limits established for the particular board.
9. Set the Jumpers to the following position  
J2: all 5 positions set to 1-2 (side closest to JTAG)  
J4: OPEN  
J5: 2-3  
J10: 1-2 for 1080p, OPEN for XGA  
J11: OPEN
10. Manufacturer's Serial Number (MSN) – T40-wwyy-nnn  
T40 – Factory internal code

## **DLP Discovery 4100 Circuit Card Assembly Main Board**

ww – Week of year (1-53)  
yy – Year (2009 is '09')  
nnn – Serialized code

### **Bill of Material**

See 2510301\_BOM\_CCA\_B.xls file on Extranet.

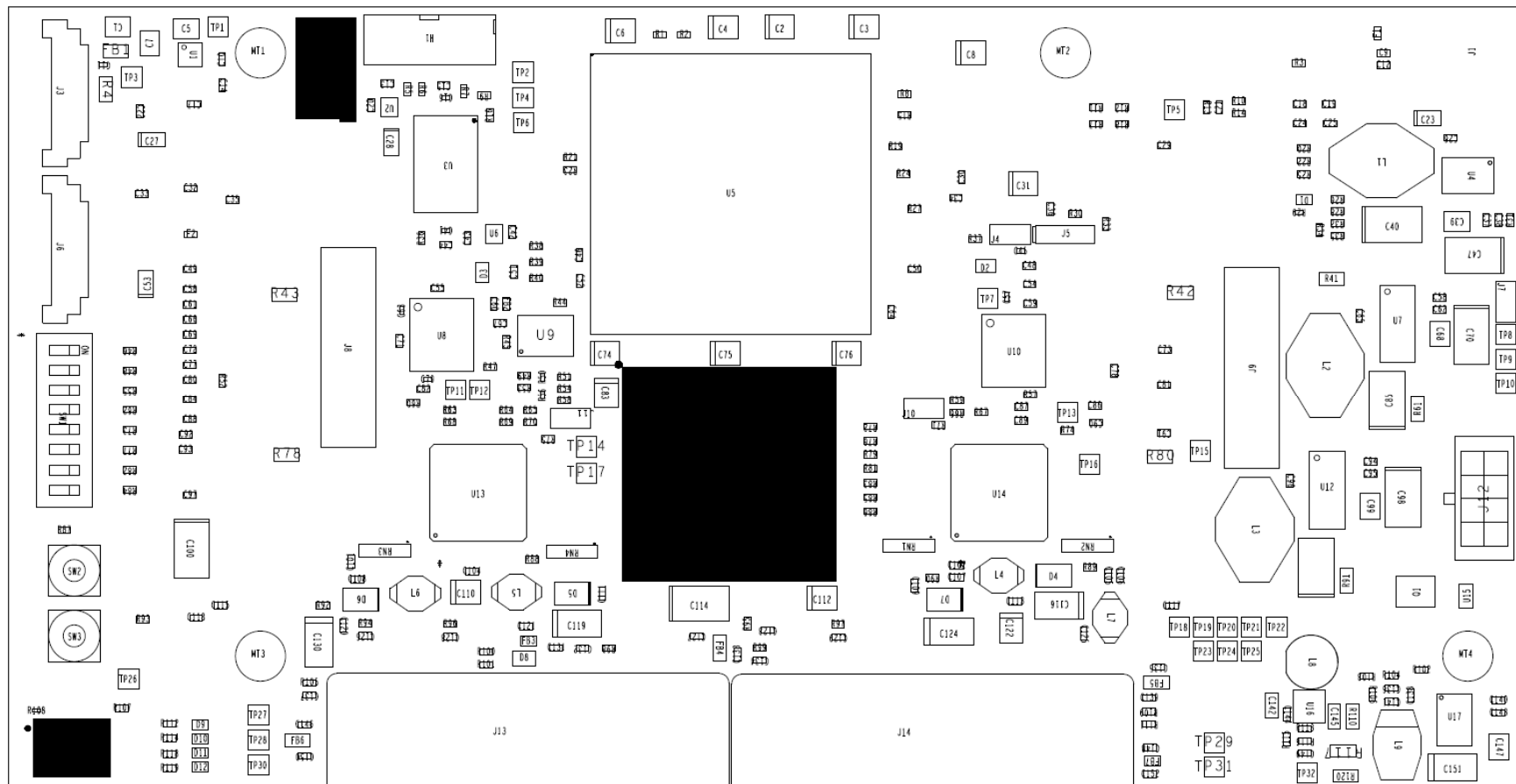
### **4. Cross Reference**

See 2510301\_BOM\_CCA\_B.xls file on Extranet.

## DLP Discovery 4100 Circuit Card Assembly Main Board

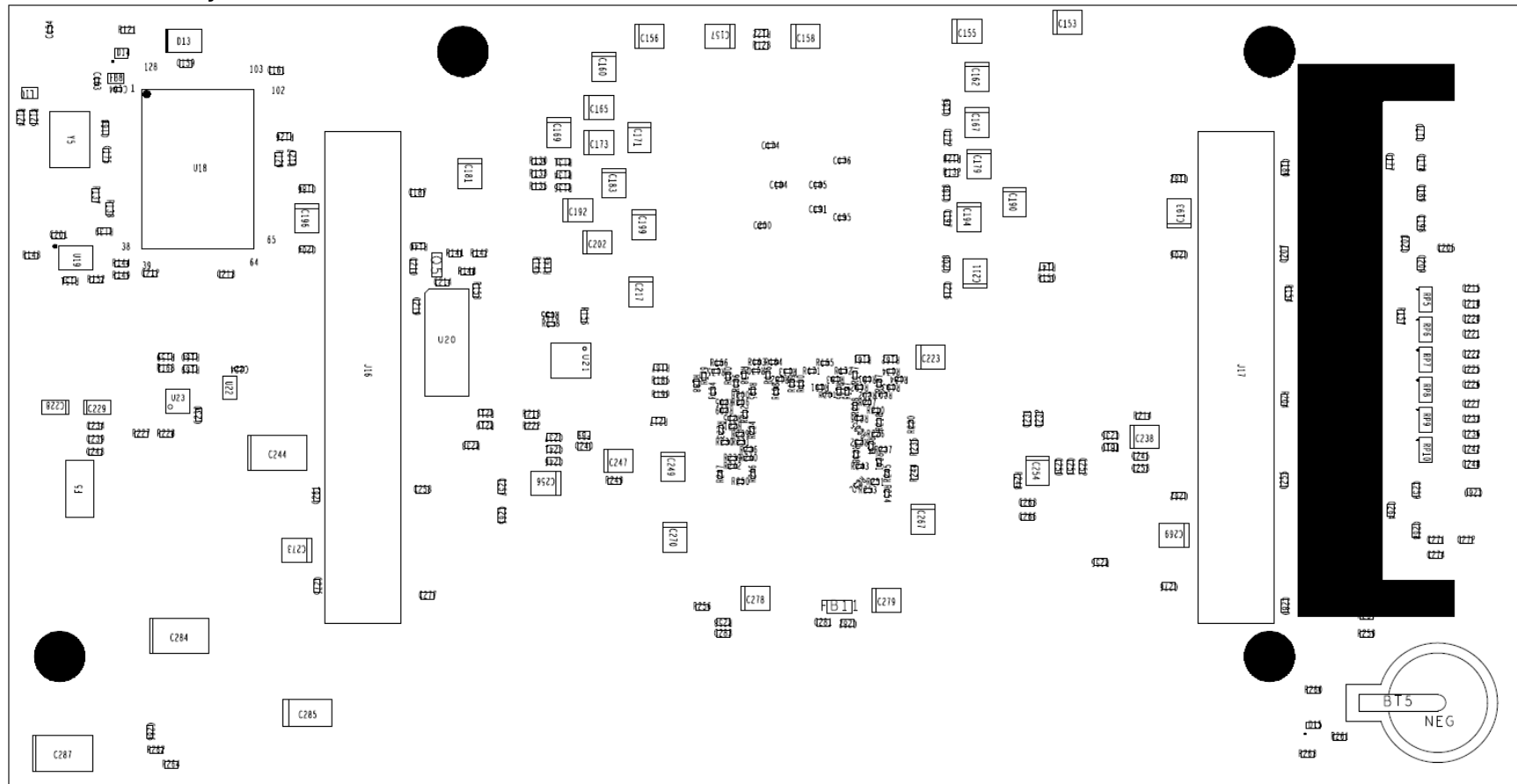
### 6. Assembly View

#### 6.1 Primary Side



## DLP Discovery 4100 Circuit Card Assembly Main Board

### 6.2 Secondary Side



## **DLP Discovery 4000 Circuit Card Assembly Main Board**

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